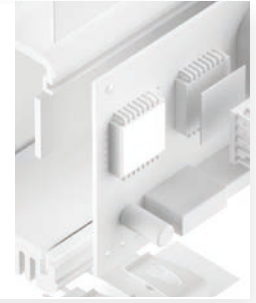


SILICONE-FREE THERMAL GREASE TGR-M-NS HALA

highly thermally conductive

TGR-M-NS is high performing silicone-free thermal grease based on an ester oil matrix. It is ideal for use in applications where a very good and highly reliable thermal transfer must be achieved. Due to the specific formulation and filling with ceramic particles the material has a high thermal conductivity. By its use the thermal contact is maximised, hence the total thermal resistance is minimised.



Release 03 / 2020

PROPERTIES

- Thermal conductivity: 2.4 W/mK
- Silicone-free
- Dispensable
- Almost zero pressure at assembly
- Dielectric strength
- Operating temperature range: -40 to 150°C

AVAILABILITY

- Syringes
- Jars 1 kg
- On request

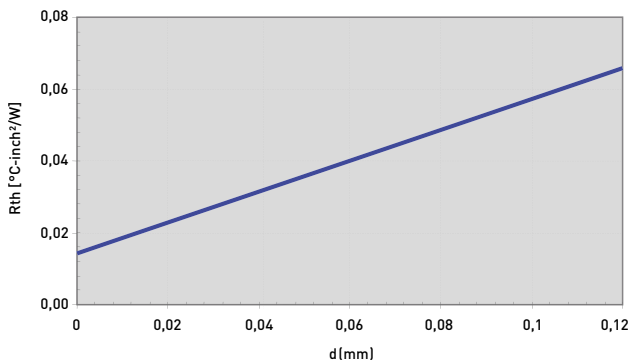
APPLICATION EXAMPLES

- Thermal link of:
- LED Boards
 - Power modules
 - RDRAMs memory modules
 - Flip Chips, DSPs , BGAs, PPGAs
- For use in Automotive applications / Power electronics / Light technology / Industrial PCs

Technical Data Sheet

PROPERTY	UNIT	TGR-M-NS
MATERIAL		
Colour		Ceramic filled thermal grease
Density	g /cm ³	White
Viscosity @ 25°C (Brookfield @ 10 rpm, 25 °C)	Pas	3.2
RoHS Conformity	2015 / 863 / EU	110
THERMAL		
Thermal Conductivity	W/mK	Yes
Operating Temperature Range	°C	2.4
Storage Temperature	°C	- 40 to + 150
Shelf Life (from Date of Manufacturing, unopened)	Months @ RT	< 35
ELECTRIC		
Dielectric Strength	kV / mm	12
		4,5

All data without warranty and subject to change. Please contact us for further data and information.



All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.